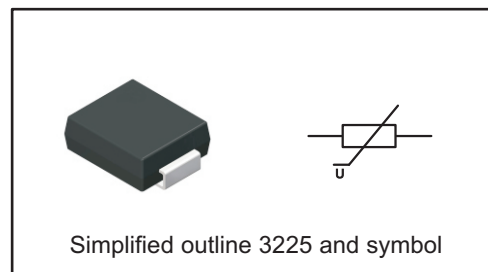




Surface-mount varistor device

FEATURES

- Wide operating voltage (V1mA) range from 240V to 560V
- Fast responding to transient over-voltage
- Large absorbing transient energy capability
- Low clamping ratio and no following-on current



MECHANICAL DATA

- Case: 3225
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 0.505g / 0.0178oz

Mechanical Requirements

Solderability	Min. 95% of The Terminal Should Be Covered With Solder Uniformly	Solder Temp: 265±5°C Immersed Time: 2±0.5Sec.
Resistance of soldering heat	$\Delta V_{1mA}/V_{1mA} \leq \pm 10\%$	Solder Temp: 260±5°C
		Immersed Time: 10±1Sec.

Environmental Requirements

High Temperature Storage	$\Delta V_{1mA}/V_{1mA} \leq \pm 10\%$	Ambient Temp: 125±2°C Duration: 1000h		
Low Temperature Storage	$\Delta V_{1mA}/V_{1mA} \leq \pm 10\%$	Ambient Temp: -40±2°C Duration: 1000h		
High Humidity Storage/Damp Heat	$\Delta V_{1mA}/V_{1mA} \leq \pm 10\%$	Ambient Temp: 40±2°C 90-95% R.H. Duration: 1000h		
High Temperature Load	$\Delta V_{1mA}/V_{1mA} \leq \pm 10\%$	Ambient temp: 85±2°C Duration: 1000h Load: Max. Allowable Voltage		
Damp Heat Load/ Humidity Load	$\Delta V_{1mA}/V_{1mA} \leq \pm 10\%$	1. Temperature : 40±2°C 2. Humidity : 90~95% RH 3. Rated working voltage applied 4. Time : 500±2 hours 5. Test after placing in ambient temperature for 24 hours.		
Temperature Cycle	$\Delta V_{1mA}/V_{1mA} \leq \pm 10\%$	Step	Temperature	Period
		1	-50°C	30min
		2	Room Temp	15min
		3	125°C	30min
4	Room Temp	15min		
Operating Temperature Range	-40°C ~ +125°C	-40°C ~ +125°C		
Storage Temperature Range	-55°C ~ +125°C	-55°C ~ +125°C		



Characteristics at Ta = 25°C

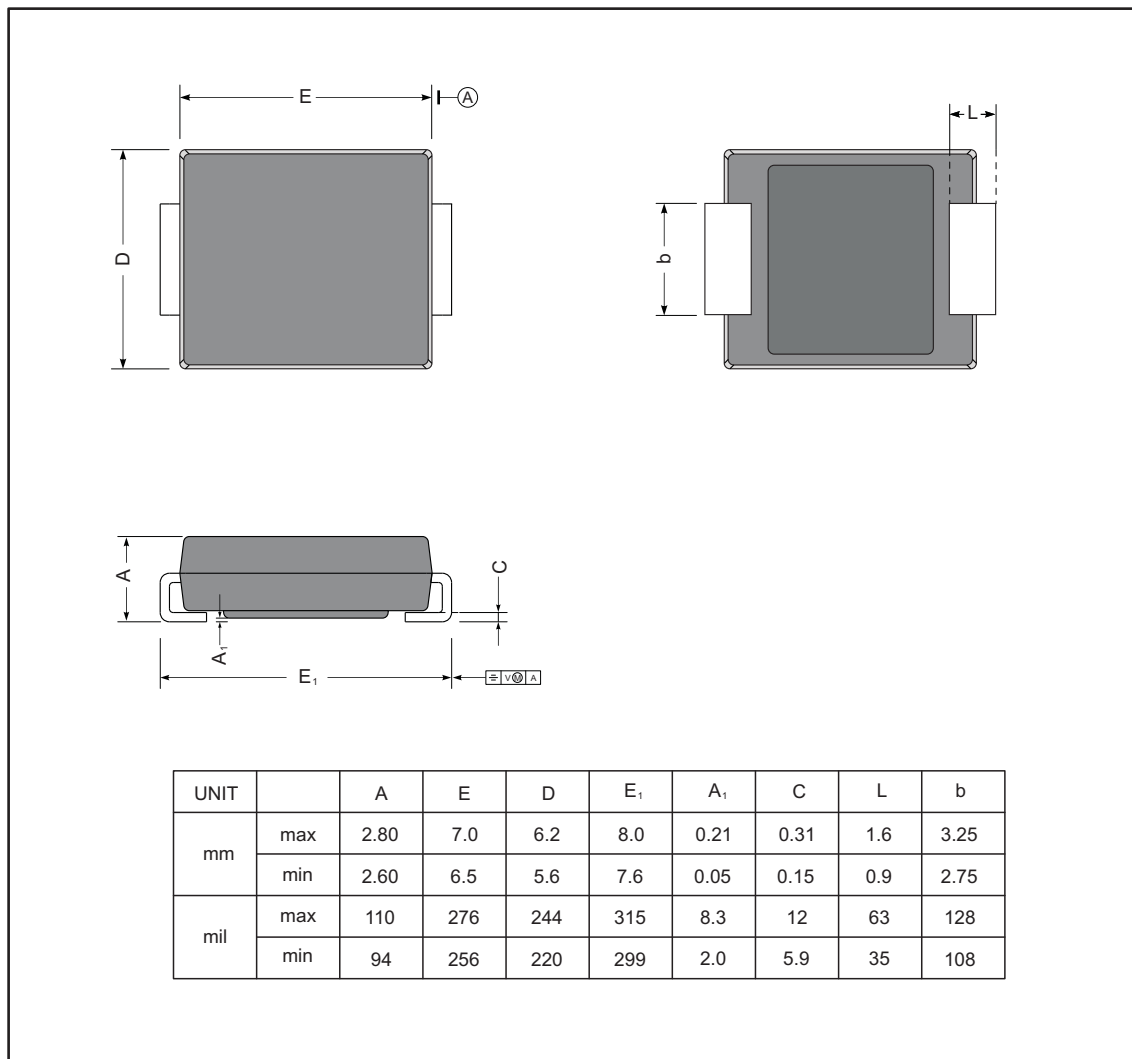
Type Number	Marking	Maximum Allowable Voltage		Varistor Voltage	Maximum Clamping Voltage		Withstanding Surge Current I(A)	Maximum Energy (J)	Rated Power W	Typical Capacitance (Reference) @1KHz(pF)
		V _{AC}	V _{DC}	V _{1mA}	I _T	V _C				
		V	V	V	A	V				
3225D241KJ	3225D241KJ	150	200	240(216~264)	5	415	800	10.5	0.1	100
3225D271KJ	3225D271KJ	175	225	270(243~297)	5	475	800	11	0.1	95
3225D301KJ	3225D301KJ	190	250	300(270~330)	5	520	800	12	0.1	85
3225D331KJ	3225D331KJ	210	275	330(297~363)	5	570	800	13	0.1	75
3225D361KJ	3225D361KJ	230	300	360(324~396)	5	620	800	16	0.1	70
3225D391KJ	3225D391KJ	250	320	390(351~429)	5	675	800	17	0.1	65
3225D431KJ	3225D431KJ	275	350	430(387~473)	5	745	800	20	0.1	60
3225D471KJ	3225D471KJ	300	385	470(423~517)	5	810	800	21	0.1	55
3225D511KJ	3225D511KJ	320	415	510(459~561)	5	845	800	22.5	0.1	50
3225D561KJ	3225D561KJ	350	460	560(504~616)	5	920	800	24	0.1	50



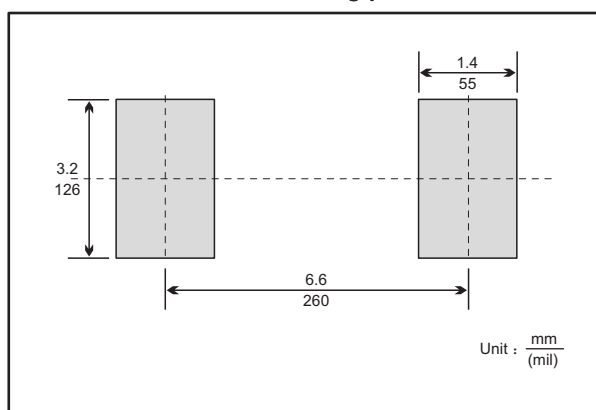
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

3225



The recommended mounting pad size





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